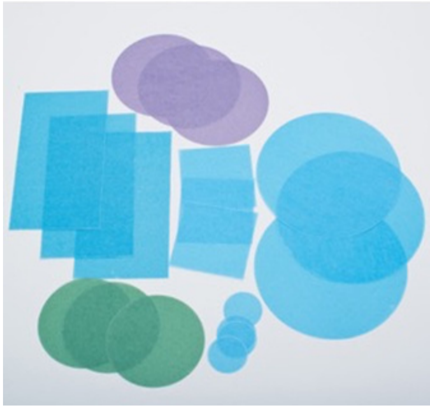
IMAGETRANSFORMS

WaferGrip™



Advanced Adhesives

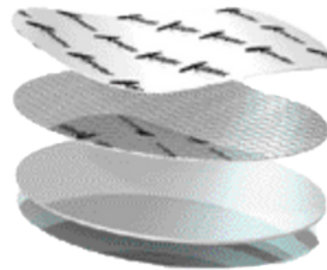
WaferGrip™ (WG) Adhesives are advanced composite film adhesives. Engineered to bond wafers, thin film heads, optics and other substrates during dicing, grinding, lapping and polishing. Removal leaves no debris or residues.

Applications

- HDD Head Polishing
- Grinding Protection
- Wafer Handline
- Protection (i.e. MEMS)

How it Works

WaferGrip Adhesives consist of precisely combined Ethylene Vinyl Acetate (EVA) polymers. Heat activated to bond two surfaces together. A typical application is the bonding of wafers to mounting substrates for the thinning process.



Formulations

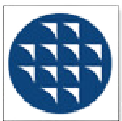
1. Standard Temperature
2. Low Temp
3. High Temp

Conductive features are available through the addition of ultra-pure fine powder infused Silver(Ag).

Configurations

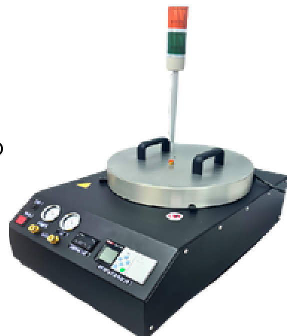
1. **Release Paper,** used for many standard. applications including wafer dicing and wafer thinning.
2. **Polyester Film**, used as a temporary substrate that allows the user to cut through the wafer into the substrate below.
3. **Double Sided Polyester Film**

Alls configurations resistant to water, IPA, Acetone, KOH etch solutions, photoresist strippers.



WaferBonder™

DXB Series Wafer Bonders are designed to bond wafers using Wafergrip.The DXB Series Wafer Bonder is for mounting a wafer to the substrate.
Improves bond quality and repeatability while improving process time during lapping, polishing, or dicing.



StripAid™

Biodegradable hydrocarbon plasticiser used for de-bonding WaferGrip.
The non-hazardous formulation makes StripAid X Solvent a popular choice for processes in which environmental impact is a particular concern.

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